


MATERIAL DECLARATION SHEET



Package Type	PTVS20-015C-H			
Product Line	Semiconductor Products			
Compliance Date	7 th July 2022			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.983515	Amorphous Silica	60676-86-0	88.0000	48.292958	49.55478
				Solid Epoxy Resin 1	Proprietary	4.6000	0.160937	
				Solid Epoxy Resin 2	Proprietary	4.5000	0.137519	
				Phenol Resin	Proprietary	2.4000	0.719716	
				Carbon Black	1333-86-4	0.5000	0.243654	
2	Leadframe	Copper Alloy	0.368898	Copper	7440-50-8	97.4325	18.182051	18.58705
				Iron	7439-89-6	2.3500	0.385560	
				Phosphorus	7723-14-0	0.1250	0.004775	
				Zinc	7440-66-6	0.0825	0.012296	
				Lead	7439-92-1	0.0100	0.002367	
3	Electrodes	Copper Alloy	0.263314	Copper	7440-50-8	95.4850	12.570273	13.26718
				Silver	7440-22-4	4.5000	0.695120	
				Iron	7439-89-6	0.0050	0.000579	
				Lead	7439-92-1	0.0050	0.000835	
				Zinc	7440-66-6	0.0030	0.000315	
4	Solder Paste	Solder	0.132638	Phosphorus	7723-14-0	0.0020	0.000054	6.68304
				Lead*	7439-92-1	92.5000	6.305674	
				Tin	7440-31-5	5.0000	0.219717	
				Silver	7440-22-4	2.5000	0.157649	
				Silicon	7440-21-3	89.5636	5.055676	
5	Chip	Silicon	0.112032	Aluminum	7429-90-5	8.2469	0.465521	5.64479
				Nickel	7440-02-0	0.9769	0.055146	
				Titanium	7440-32-6	0.5735	0.032371	
				Silver	7440-22-4	0.6391	0.036077	
				Copper	7440-50-8	95.4850	5.078081	
6	Clip	Copper Alloy	0.106372	Silver	7440-22-4	4.5000	0.280812	5.35961
				Iron	7439-89-6	0.0050	0.000234	
				Lead	7439-92-1	0.0050	0.000337	
				Zinc	7440-66-6	0.0030	0.000127	
				Phosphorus	7723-14-0	0.0020	0.000022	
7	Terminal Finish	Tin	0.017933	Tin	7440-31-5	100.0000	0.903547	0.90355
		Total weight	1.98470					

* 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)